



PlasmaSolv[®] Products - HDA[®] Technology

Aqueous organic mixtures formulated to effectively remove residues from substrate surfaces after via, poly and metal etch processes used in the microelectronics industry.

PlasmaSolv[®] products are designed to remove post etch residue. These products perform at low operating temperatures, well below the flashpoint of the chemistry, providing a safe chemical process as well as extending bath life.

EKC325[™]

Post-etch residue remover specifically developed for sub-0.25 μ m processes. It is enabling technology for the removal of residues from the wafer surface after etching with gases such as CF₄ or HBr/Cl₂. EKC325[™] contains no SARA Title III components.

EKC311[™]

Post-etch residue remover with improved Ti compatibility containing no SARA Title III components. Designed to remove ashed photoresist residue, organic polymer, and organometallic etch residue with maximum Ti retention and enhanced mobile metal ion chelation.

EKC270[™]

Post-etch residue remover with improved Ti compatibility. Formulated to remove ashed photoresist residue, organic polymer, and organometallic etch residue while maintaining optimum metal stack integrity.

EKC265[™]

The initial product in the series formulated to remove photoresist residue generated after etch processes. Effective with or without oxygen ash processing.

EKC245[™]

Specifically designed to clean post-etch residues generated during the volume production of high capacity DRAM devices. Also used to clean HBr-etched polysilicon. Able to remove residues after metal etching quartz furnace tubes, etcher parts and similar equipment.

EKC220[™]

This product is similar to EKC265[™] but utilizes hydroxylamine more efficiently as a result of product optimization. Originally developed to address Ti undercut with a cost effective formulation.

Covered by one or more of the following patents:

U.S. Patent Numbers: 5,279,771; 5,334,332; 5,381,807; 5,482,566; 5,672,577; 5,902,780; 5,911,835; 6,000,411

Japanese Patent: 2,691,952; 3,048,207

European Patent: 485,161

Korean Patent: 150,411

Other U.S. and Foreign Patents Pending

EKC offers applications engineering support for all products. This includes product development and sustaining engineering solutions. On-site consulting, process evaluation and/or additional wafer testing are available through EKC's applications engineering or R & D as needed.

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DuPont Electronic Technologies

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